

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|-------|---|---|------------------|---------|------------------|
| L7 | 65065 | CMP or "chemical mechanical polishing" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/29 13:44 |
| L8 | 1431 | slurry same filter\$3 same recirculat\$4 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/29 15:32 |
| L9 | 38 | 7 and 8 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/29 13:44 |
| L10 | 575 | slurry and filter\$3 and recirculat\$4 and abrasive | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/29 16:24 |
| L11 | 131 | 10 and 7 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/29 13:51 |
| L12 | 4555 | slurry and filter\$3 and mix\$4 and abrasive | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/29 14:18 |
| L13 | 730 | 12 and 7 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/29 14:19 |
| L14 | 685 | 13 and semiconductor | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/29 14:19 |

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|-----|------|--|---|----|----|------------------|
| L15 | 676 | slurry same filter\$3 same abrasive | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/29 15:32 |
| L16 | 1331 | slurry and filter\$3 and (recirculat\$4 or recycl\$4) and abrasive | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/29 16:25 |
| L17 | 6372 | slurry same filter\$3 same (recirculat\$4 or recycl\$4) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/29 16:24 |
| L18 | 227 | 17 and abrasive | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/29 16:25 |